



PATENT
740819-405

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Shinichi IMAI

Serial No. 09/630,680

Filed: August 1, 2000

For: PLASMA PROCESSING METHOD

) Group Art Unit: 1746

) Examiner: Ahmed, Shamim

) CERTIFICATE OF MAILING

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) Washington, D.C. 20231, on May 30, 2002.

) Gwyn F. Cantrell
Gwyn F. Cantrell

AMENDMENT

Honorable Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Examiner's non-final Office Action mailed January 30, 2002, the period for responding having been extended one (1) month to May 30, 2002, please consider the following amendments and remarks in connection with the above-identified application.

IN THE CLAIMS:

Please cancel claims 2, 5, 8, 11 and 13-18 without prejudice to or disclaimer of the subject matter disclosed therein.

Please amend claims 1, 4, 7 and 10 as follows. Claims 1, 4, 7 and 10 are presented below in their amended form. The amendments to the above-noted claims are outlined in an Attachment to the Amendment using the conventional indication method of bracketing and underlining.

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1. (Amended) A plasma processing method comprising the steps of:
placing a substrate inside a reaction chamber of a plasma processing system, a silicon dioxide film having been formed on the surface of the substrate;

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